

FEATURES

- 44 V supply maximum ratings**
- V_{SS} to V_{DD} analog signal range**
- Low on resistance (100 Ω maximum)**
- Low power (I_{SUPPLY} < 75 μA)**
- Fast switching**
- Break-before-make switching action**
- Plug-in replacement for DG408/DG409**

APPLICATIONS

- Audio and video routing**
- Automatic test equipment**
- Data acquisition systems**
- Battery-powered systems**
- Sample-and-hold systems**
- Communication systems**

GENERAL DESCRIPTION

The ADG408/ADG409 are monolithic CMOS analog multiplexers comprising eight single channels and four differential channels, respectively. The ADG408 switches one of eight inputs to a common output as determined by the 3-bit binary address lines A0, A1, and A2. The ADG409 switches one of four differential inputs to a common differential output, as determined by the 2-bit binary address lines A0 and A1. An EN input on both devices is used to enable or disable the device. When the device is disabled, all channels are switched off.

The ADG408/ADG409 are designed on an enhanced LC²MOS process that provides low power dissipation yet gives high switching speed and low on resistance. Each channel conducts equally well in both directions when on and has an input signal range that extends to the supplies. In the off condition, signal levels up to the supplies are blocked. All channels exhibit break-before-make switching action, preventing momentary shorting when switching channels. Inherent in the design is low charge injection for minimum transients when switching the digital inputs.

The ADG408/ADG409 are improved replacements for the DG408/DG409 analog multiplexers.

FUNCTIONAL BLOCK DIAGRAMS

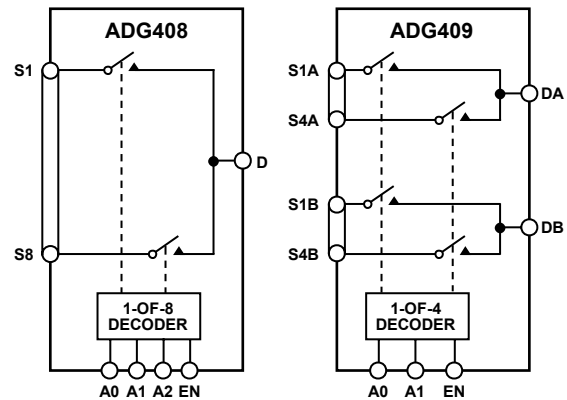


Figure 1.

PRODUCT HIGHLIGHTS

1. **Extended Signal Range.** The ADG408/ADG409 are fabricated on an enhanced LC²MOS process, giving an increased signal range that extends to the supply rails.
2. **Low Power Dissipation.**
3. **Low R_{ON}.**
4. **Single-Supply Operation.** For applications where the analog signal is unipolar, the ADG408/ADG409 can be operated from a single rail power supply. The parts are fully specified with a single 12 V power supply and remain functional with single supplies as low as 5 V.

Rev. C

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TABLE OF CONTENTS

| | | | |
|--------------------------------|---|--|----|
| Features | 1 | Absolute Maximum Ratings | 6 |
| Applications..... | 1 | ESD Caution..... | 6 |
| Functional Block Diagrams..... | 1 | Pin Configurations and Function Descriptions | 7 |
| General Description | 1 | Typical Performance Characteristics | 8 |
| Product Highlights | 1 | Test Circuits..... | 11 |
| Revision History | 2 | Terminology | 13 |
| Specifications..... | 3 | Outline Dimensions | 14 |
| Dual Supply | 3 | Ordering Guide | 16 |
| Single Supply | 4 | | |

REVISION HISTORY

10/06—Rev. B to Rev. C

| | |
|-----------------------------------|-----------|
| Updated Format..... | Universal |
| Changes to Table 3..... | 6 |
| Inserted Table 4 and Table 5..... | 7 |
| Updated Outline Dimensions | 14 |
| Changes to Ordering Guide | 15 |

3/03—Rev. A to Rev. B

| | |
|----------------------------------|----|
| Changes to Ordering Guide | 4 |
| Updated Outline Dimensions | 11 |

2/01—Revision 0: Initial Version

SPECIFICATIONS

DUAL SUPPLY

$V_{DD} = 15\text{ V}$, $V_{SS} = -15\text{ V}$, $GND = 0\text{ V}$, unless otherwise noted.

Table 1.

| Parameter | B Version | | T Version | | Unit | Test Conditions/Comments |
|--|-----------|----------------------|-----------|----------------------|-------------------|---|
| | +25°C | -40°C to +85°C | +25°C | -55°C to +125°C | | |
| ANALOG SWITCH | | | | | | |
| Analog Signal Range | | V_{SS} to V_{DD} | | V_{SS} to V_{DD} | V | |
| R_{ON} | 40 | | 40 | | Ω typ | $V_D = \pm 10\text{ V}$, $I_S = -10\text{ mA}$ |
| | 100 | 125 | 100 | 125 | Ω max | |
| ΔR_{ON} | 15 | | 15 | | Ω max | $V_D = +10\text{ V}$, -10 V |
| LEAKAGE CURRENTS | | | | | | |
| Source Off Leakage I_S (OFF) | ± 0.5 | ± 50 | ± 0.5 | ± 50 | nA max | $V_D = \pm 10\text{ V}$, $V_S = \mp 10\text{ V}$; see Figure 19 |
| Drain Off Leakage I_D (OFF) | | | | | | $V_D = \pm 10\text{ V}$; $V_S = \mp 10\text{ V}$; see Figure 20 |
| ADG408 | ± 1 | ± 100 | ± 1 | ± 100 | nA max | |
| ADG409 | ± 1 | ± 50 | ± 1 | ± 50 | nA max | |
| Channel On Leakage I_D , I_S (ON) | | | | | | $V_S = V_D = \pm 10\text{ V}$; see Figure 21 |
| ADG408 | ± 1 | ± 100 | ± 1 | ± 100 | nA max | |
| ADG409 | ± 1 | ± 50 | ± 1 | ± 50 | nA max | |
| DIGITAL INPUTS | | | | | | |
| Input High Voltage, V_{INH} | | 2.4 | | 2.4 | V min | |
| Input Low Voltage, V_{INL} | | 0.8 | | 0.8 | V max | |
| Input Current | | | | | | |
| I_{INL} or I_{INH} | | ± 10 | | ± 10 | μA max | $V_{IN} = 0$ or V_{DD} |
| C_{IN} , Digital Input Capacitance | 8 | | 8 | | pF typ | $f = 1\text{ MHz}$ |
| DYNAMIC CHARACTERISTICS¹ | | | | | | |
| $t_{TRANSITION}$ | | 120 | | 120 | ns typ | $R_L = 300\ \Omega$, $C_L = 35\text{ pF}$; |
| | | 250 | | 250 | ns max | $V_{S1} = \pm 10\text{ V}$, $V_{S8} = \mp 10\text{ V}$; see Figure 22 |
| t_{OPEN} | 10 | 10 | 10 | 10 | ns min | $R_L = 300\ \Omega$, $C_L = 35\text{ pF}$; |
| | | | | | | $V_S = 5\text{ V}$; see Figure 23 |
| t_{ON} (EN) | 85 | 125 | 85 | 125 | ns typ | $R_L = 300\ \Omega$, $C_L = 35\text{ pF}$; |
| | 150 | 225 | 150 | 225 | ns max | $V_S = 5\text{ V}$; see Figure 24 |
| t_{OFF} (EN) | | 65 | | 65 | ns typ | $R_L = 300\ \Omega$, $C_L = 35\text{ pF}$; |
| | | 150 | | 150 | ns max | $V_S = 5\text{ V}$; see Figure 24 |
| Charge Injection | 20 | | 20 | | pC typ | $V_S = 0\text{ V}$, $R_S = 0\ \Omega$, $C_L = 10\text{ nF}$; see Figure 25 |
| OFF Isolation | -75 | | -75 | | dB typ | $R_L = 1\text{ k}\Omega$, $f = 100\text{ kHz}$; |
| | | | | | | $V_{EN} = 0\text{ V}$; see Figure 26 |
| Channel-to-Channel Crosstalk | 85 | | 85 | | dB typ | $R_L = 1\text{ k}\Omega$, $f = 100\text{ kHz}$; see Figure 27 |
| C_S (OFF) | 11 | | 11 | | pF typ | $f = 1\text{ MHz}$ |
| C_D (OFF) | | | | | | $f = 1\text{ MHz}$ |
| ADG408 | 40 | | 40 | | pF typ | |
| ADG409 | 20 | | 20 | | pF typ | |
| C_D , C_S (ON) | | | | | | $f = 1\text{ MHz}$ |
| ADG408 | 54 | | 54 | | pF typ | |
| ADG409 | 34 | | 34 | | pF typ | |

ADG408/ADG409

| Parameter | B Version | | T Version | | Unit | Test Conditions/Comments |
|---------------------------|-----------|----------------|-----------|-----------------|-------------------|--|
| | +25°C | -40°C to +85°C | +25°C | -55°C to +125°C | | |
| POWER REQUIREMENTS | | | | | | |
| I_{DD} | | 1 | | 1 | $\mu\text{A typ}$ | $V_{IN} = 0\text{ V}, V_{EN} = 0\text{ V}$ |
| | | 5 | | 5 | $\mu\text{A max}$ | |
| I_{SS} | | 1 | | 1 | $\mu\text{A typ}$ | |
| | | 5 | | 5 | $\mu\text{A max}$ | |
| I_{DD} | 100 | | 100 | | $\mu\text{A typ}$ | $V_{IN} = 0\text{ V}, V_{EN} = 2.4\text{ V}$ |
| | 200 | 500 | 200 | 500 | $\mu\text{A max}$ | |

¹ Guaranteed by design, not subject to production test.

SINGLE SUPPLY

$V_{DD} = 12\text{ V}, V_{SS} = 0\text{ V}, \text{GND} = 0\text{ V}$, unless otherwise noted.

Table 2.

| Parameter | B Version | | T Version | | Unit | Test Conditions/Comments |
|--|-----------|----------------|-----------|-----------------|---------------------|---|
| | +25°C | -40°C to +85°C | +25°C | -55°C to +125°C | | |
| ANALOG SWITCH | | | | | | |
| Analog Signal Range | | 0 to V_{DD} | | 0 to V_{DD} | V | |
| R_{ON} | 90 | | 90 | | $\Omega\text{ typ}$ | $V_D = 3\text{ V}, 10\text{ V}, I_S = -1\text{ mA}$ |
| LEAKAGE CURRENTS | | | | | | |
| Source Off Leakage I_S (OFF) | ± 0.5 | ± 50 | ± 0.5 | ± 50 | nA max | $V_D = 8\text{ V}/0\text{ V}, V_S = 0\text{ V}/8\text{ V}$; see Figure 19 |
| Drain Off Leakage I_D (OFF) | | | | | | $V_D = 8\text{ V}/0\text{ V}, V_S = 0\text{ V}/8\text{ V}$; see Figure 20 |
| ADG408 | ± 1 | ± 100 | ± 1 | ± 100 | nA max | |
| ADG409 | ± 1 | ± 50 | ± 1 | ± 50 | nA max | |
| Channel On Leakage I_D, I_S (ON) | | | | | | $V_S = V_D = 8\text{ V}/0\text{ V}$; see Figure 21 |
| ADG408 | ± 1 | ± 100 | ± 1 | ± 100 | nA max | |
| ADG409 | ± 1 | ± 50 | ± 1 | ± 50 | nA max | |
| DIGITAL INPUTS | | | | | | |
| Input High Voltage, V_{INH} | | 2.4 | | 2.4 | V min | |
| Input Low Voltage, V_{INL} | | 0.8 | | 0.8 | V max | |
| Input Current | | | | | | |
| I_{INL} or I_{INH} | | ± 10 | | ± 10 | $\mu\text{A max}$ | $V_{IN} = 0$ or V_{DD} |
| C_{IN} , Digital Input Capacitance | 8 | | 8 | | pF typ | $f = 1\text{ MHz}$ |
| DYNAMIC CHARACTERISTICS¹ | | | | | | |
| $t_{TRANSITION}$ | 130 | | 130 | | ns typ | $R_L = 300\ \Omega, C_L = 35\text{ pF}$; $V_{S1} = 8\text{ V}/0\text{ V}, V_{S8} = 0\text{ V}/8\text{ V}$; see Figure 22 |
| t_{OPEN} | 10 | | 10 | | ns typ | $R_L = 300\ \Omega, C_L = 35\text{ pF}$; |
| t_{ON} (EN) | 140 | | 140 | | ns typ | $V_S = 5\text{ V}$; see Figure 23 $R_L = 300\ \Omega, C_L = 35\text{ pF}$; |
| t_{OFF} (EN) | 60 | | 60 | | ns typ | $V_S = 5\text{ V}$; see Figure 24 $R_L = 300\ \Omega, C_L = 35\text{ pF}$; |
| Charge Injection | 5 | | 5 | | pC typ | $V_S = 0\text{ V}, R_S = 0\ \Omega, C_L = 10\text{ nF}$; see Figure 25 |
| Off Isolation | -75 | | -75 | | dB typ | $R_L = 1\text{ k}\Omega, f = 100\text{ kHz}$; $V_{EN} = 0\text{ V}$; see Figure 26 |

| Parameter | B Version | | T Version | | Unit | Test Conditions/Comments |
|------------------------------|-----------|----------------|-----------|-----------------|-------------------|---|
| | +25°C | -40°C to +85°C | +25°C | -55°C to +125°C | | |
| Channel-to-Channel Crosstalk | 85 | | 85 | | dB typ | $R_L = 1\text{ k}\Omega$, $f = 100\text{ kHz}$; see Figure 27 |
| C_S (OFF) | 11 | | 11 | | pF typ | $f = 1\text{ MHz}$ |
| C_D (OFF) | | | | | | $f = 1\text{ MHz}$ |
| ADG408 | 40 | | 40 | | pF typ | |
| ADG409 | 20 | | 20 | | pF typ | |
| C_D , C_S (ON) | | | | | | $f = 1\text{ MHz}$ |
| ADG408 | 54 | | 54 | | pF typ | |
| ADG409 | 34 | | 34 | | pF typ | |
| POWER REQUIREMENTS | | | | | | |
| I_{DD} | | 1 | | 1 | $\mu\text{A typ}$ | $V_{IN} = 0\text{ V}$, $V_{EN} = 0\text{ V}$ |
| | | 5 | | 5 | $\mu\text{A max}$ | |
| I_{DD} | 100 | | 100 | | $\mu\text{A typ}$ | $V_{IN} = 0\text{ V}$, $V_{EN} = 2.4\text{ V}$ |
| | 200 | 500 | 200 | 500 | $\mu\text{A max}$ | |

¹ Guaranteed by design, not subject to production test.

ABSOLUTE MAXIMUM RATINGS

T_A = 25°C, unless otherwise noted.

Table 3.

| Parameter | Rating |
|--|---|
| V _{DD} to V _{SS} | 44 V |
| V _{DD} to GND | −0.3 V to +32 V |
| V _{SS} to GND | +0.3 V to −32 V |
| Analog, Digital Inputs | V _{SS} − 2 V to V _{DD} + 2 V or 20 mA, whichever occurs first |
| Continuous Current, S or D | 20 mA |
| Peak Current, S or D (Pulsed at 1 ms, 10% Duty Cycle Maximum) | 40 mA |
| Operating Temperature Range | |
| Industrial (B Version) | −40° C to +85° C |
| Extended (T Version) | −55° C to +125° C |
| Storage Temperature Range | −65° C to +150° C |
| Junction Temperature | 150° C |
| CERDIP Package, Power Dissipation | 900 mW |
| θ _{JA} , Thermal Impedance | 76° C/W |
| Lead Temperature, Soldering (10 sec) | 300° C |
| PDIP Package, Power Dissipation | 470 mW |
| θ _{JA} , Thermal Impedance | 117° C/W |
| Lead Temperature, Soldering (10 sec) | 260° C |
| TSSOP Package, Power Dissipation | 450 mW |
| θ _{JA} , Thermal Impedance | 155° C/W |
| θ _{JC} , Thermal Impedance | 50° C/W |
| SOIC Package, Power Dissipation | 600 mW |
| θ _{JA} , Thermal Impedance | 77° C/W |
| Lead Temperature, Soldering | |
| Vapor Phase (60 sec) | 215° C |
| Infrared (15 sec) | 220° C |

Stresses above those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; functional operation of the device at these or any other conditions above those indicated in the operational section of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATIONS AND FUNCTION DESCRIPTIONS



Figure 2. ADG408 Pin Configuration



Figure 3. ADG409 Pin Configuration

Table 4. ADG408 Pin Function Descriptions

| Pin No. | Mnemonic | Description |
|---------|-----------------|---|
| 1 | A0 | Logic Control Input. |
| 2 | EN | Active High Digital Input. When low, the device is disabled and all switches are off. When high, Ax logic inputs determine on switches. |
| 3 | V _{SS} | Most Negative Power Supply Potential in Dual Supplies. In single-supply applications, it can be connected to ground. |
| 4 | S1 | Source Terminal 1. Can be an input or an output. |
| 5 | S2 | Source Terminal 2. Can be an input or an output. |
| 6 | S3 | Source Terminal 3. Can be an input or an output. |
| 7 | S4 | Source Terminal 4. Can be an input or an output. |
| 8 | D | Drain Terminal. Can be an input or an output. |
| 9 | S8 | Source Terminal 8. Can be an input or an output. |
| 10 | S7 | Source Terminal 7. Can be an input or an output. |
| 11 | S6 | Source Terminal 6. Can be an input or an output. |
| 12 | S5 | Source Terminal 5. Can be an input or an output. |
| 13 | V _{DD} | Most Positive Power Supply Potential. |
| 14 | GND | Ground (0 V) Reference. |
| 15 | A2 | Logic Control Input. |
| 16 | A1 | Logic Control Input. |

Table 6. ADG408 Truth Table

| A2 | A1 | A0 | EN | ON SWITCH |
|----|----|----|----|-----------|
| X | X | X | 0 | NONE |
| 0 | 0 | 0 | 1 | 1 |
| 0 | 0 | 1 | 1 | 2 |
| 0 | 1 | 0 | 1 | 3 |
| 0 | 1 | 1 | 1 | 4 |
| 1 | 0 | 0 | 1 | 5 |
| 1 | 0 | 1 | 1 | 6 |
| 1 | 1 | 0 | 1 | 7 |
| 1 | 1 | 1 | 1 | 8 |

Table 5. ADG409 Pin Function Descriptions

| Pin No. | Mnemonic | Description |
|---------|-----------------|---|
| 1 | A0 | Logic Control Input. |
| 2 | EN | Active High Digital Input. When low, the device is disabled and all switches are off. When high, Ax logic inputs determine on switches. |
| 3 | V _{SS} | Most Negative Power Supply Potential in Dual Supplies. In single-supply applications, it can be connected to ground. |
| 4 | S1A | Source Terminal 1A. Can be an input or an output. |
| 5 | S2A | Source Terminal 2A. Can be an input or an output. |
| 6 | S3A | Source Terminal 3A. Can be an input or an output. |
| 7 | S4A | Source Terminal 4A. Can be an input or an output. |
| 8 | DA | Drain Terminal A. Can be an input or an output. |
| 9 | DB | Drain Terminal B. Can be an input or an output. |
| 10 | S4B | Source Terminal 4B. Can be an input or an output. |
| 11 | S3B | Source Terminal 3B. Can be an input or an output. |
| 12 | S2B | Source Terminal 2B. Can be an input or an output. |
| 13 | S1B | Source Terminal 1B. Can be an input or an output. |
| 14 | V _{DD} | Most Positive Power Supply Potential. |
| 15 | GND | Ground (0 V) Reference. |
| 16 | A1 | Logic Control Input. |

Table 7. ADG409 Truth Table

| A1 | A0 | EN | ON SWITCH PAIR |
|----|----|----|----------------|
| X | X | 0 | NONE |
| 0 | 0 | 1 | 1 |
| 0 | 1 | 1 | 2 |
| 1 | 0 | 1 | 3 |
| 1 | 1 | 1 | 4 |

TYPICAL PERFORMANCE CHARACTERISTICS

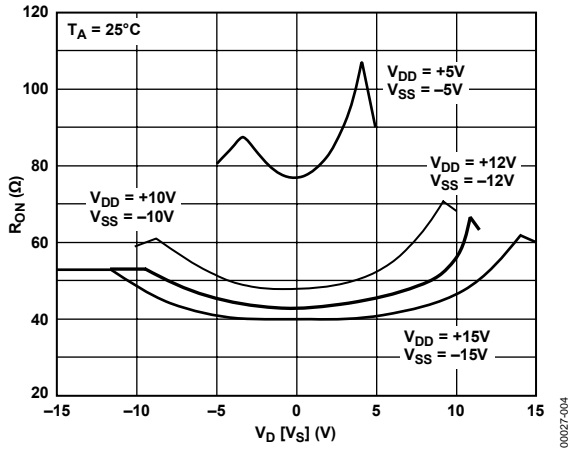


Figure 4. R_{ON} as a Function of V_D (V_S): Dual-Supply Voltage



Figure 7. R_{ON} as a Function of V_D (V_S): Single-Supply Voltage

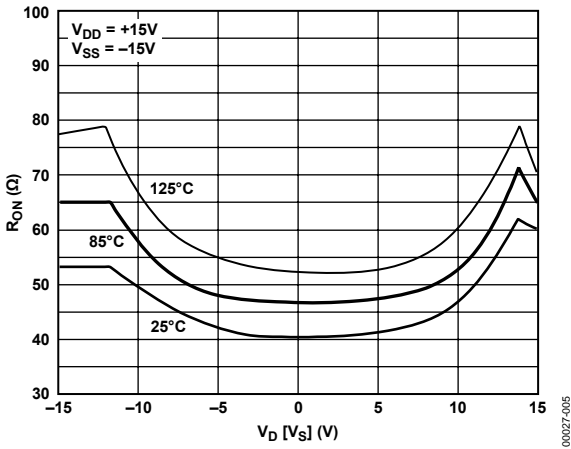


Figure 5. R_{ON} as a Function of V_D (V_S) for Different Temperatures

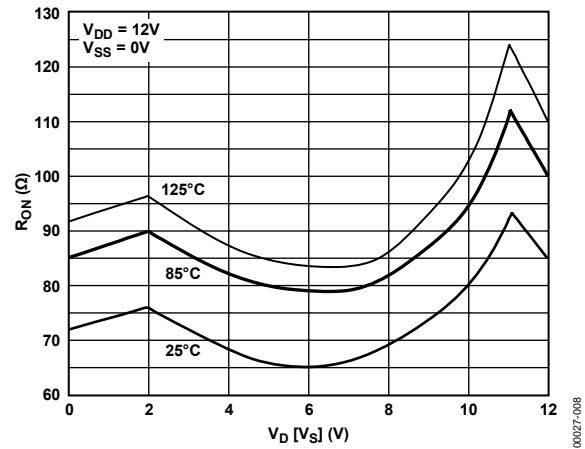


Figure 8. R_{ON} as a Function of V_D (V_S) for Different Temperature

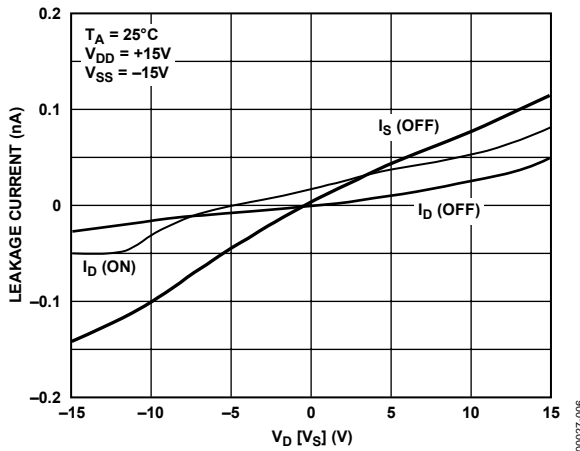


Figure 6. Leakage Currents as a Function of V_D (V_S)



Figure 9. Leakage Currents as a Function of V_D (V_S)



Figure 10. Switching Time vs. V_{IN} (Bipolar Supply)



Figure 13. Switching Time vs. V_{IN} (Single Supply)



Figure 11. Switching Time vs. Single Supply



Figure 14. Switching Time vs. Bipolar Supply

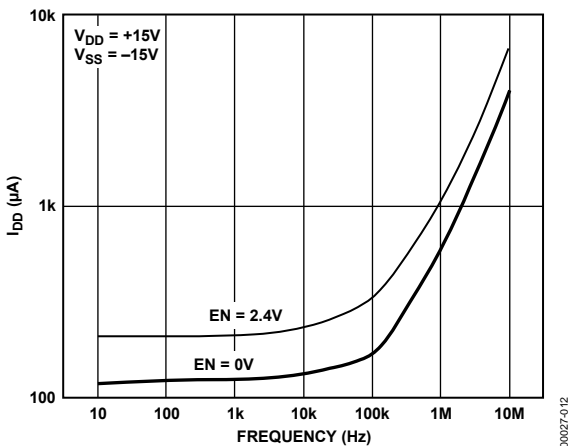


Figure 12. Positive Supply Current vs. Switching Frequency

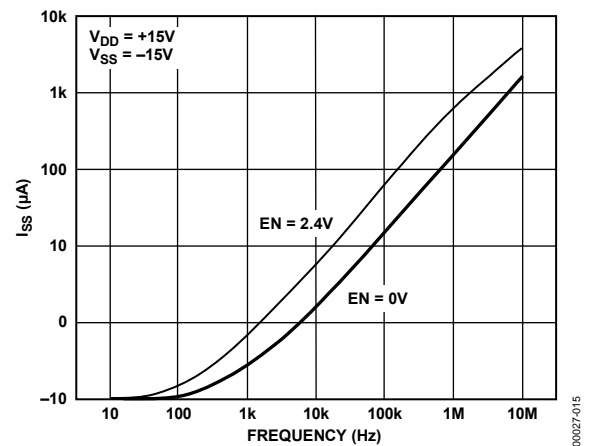


Figure 15. Negative Supply Current vs. Switching Frequency

ADG408/ADG409

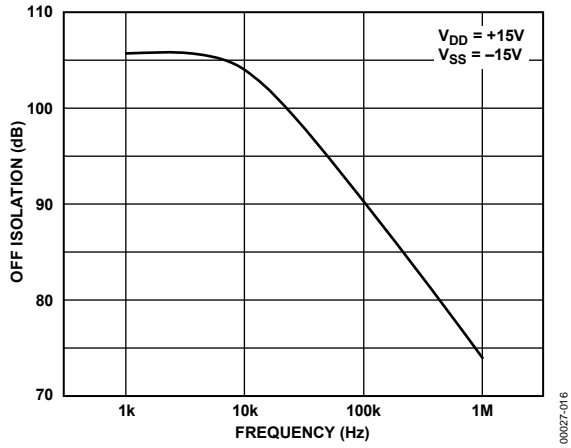


Figure 16. Off Isolation vs. Frequency

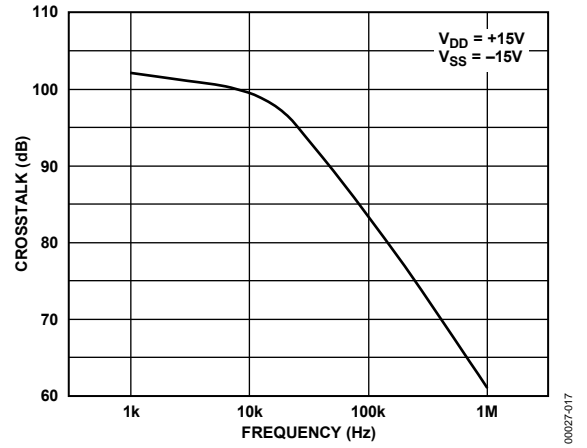


Figure 17. Crosstalk vs. Frequency

TEST CIRCUITS



Figure 18. On Resistance



Figure 20. I_b (OFF)

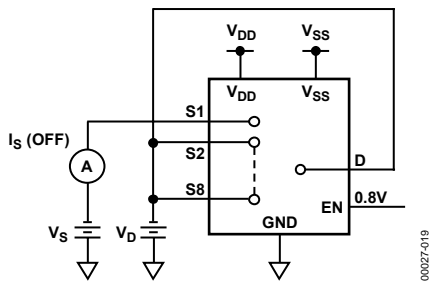


Figure 19. I_s (OFF)



Figure 21. I_b (ON)



Figure 22. Switching Time of Multiplexer, $t_{\text{TRANSITION}}$



¹SIMILAR CONNECTION FOR ADG409.

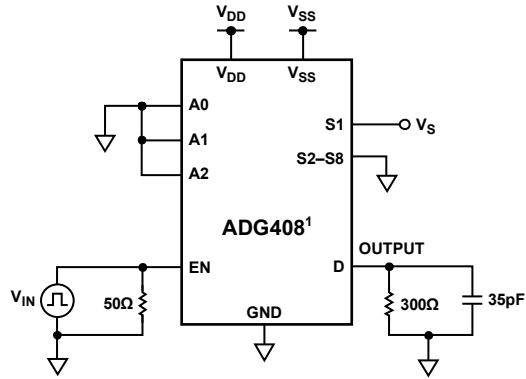
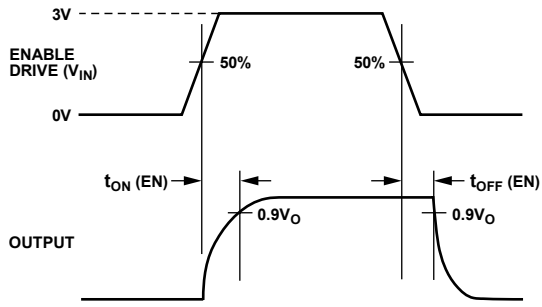


Figure 23. Break-Before-Make Delay, t_{OPEN}



¹SIMILAR CONNECTION FOR ADG409.

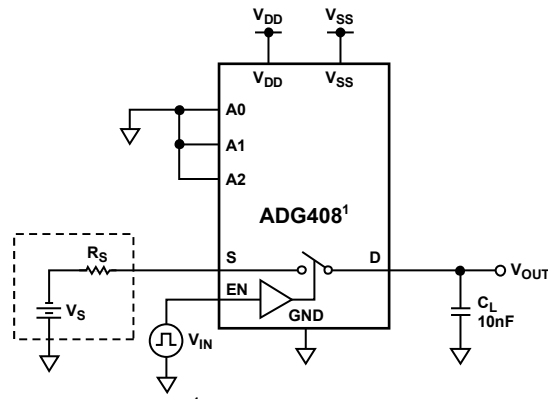
ADG408/ADG409



¹SIMILAR CONNECTION FOR ADG409.

00027-024

Figure 24. Enable Delay, $t_{ON}(EN)$, $t_{OFF}(EN)$



¹SIMILAR CONNECTION FOR ADG409.

00027-025

Figure 25. Charge Injection



OFF ISOLATION = $20 \log V_{OUT}/V_{IN}$

00027-026

Figure 26. Off Isolation



CROSSTALK = $20 \log V_{OUT}/V_{IN}$

00027-027

Figure 27. Channel-to-Channel Crosstalk

TERMINOLOGY

R_{ON}

Ohmic resistance between D and S.

ΔR_{ON}

Difference between the R_{ON} of any two channels.

I_S (OFF)

Source leakage current when the switch is off.

I_D (OFF)

Drain leakage current when the switch is off.

I_D, I_S (ON)

Channel leakage current when the switch is on.

V_D (V_S)

Analog voltage on Terminal D and Terminal S.

C_S (OFF)

Channel input capacitance for off condition.

C_D (OFF)

Channel output capacitance for off condition.

C_D, C_S (ON)

On switch capacitance.

C_{IN}

Digital input capacitance.

t_{ON} (EN)

Delay time between the 50% and 90% points of the digital input and switch on condition.

t_{OFF} (EN)

Delay time between the 50% and 90% points of the digital input and switch off condition.

$t_{TRANSITION}$

Delay time between the 50% and 90% points of the digital inputs and the switch on condition when switching from one address state to another.

t_{OPEN}

Off time measured between the 80% point of both switches when switching from one address state to another.

V_{INL}

Maximum input voltage for Logic 0.

V_{INH}

Minimum input voltage for Logic 1.

I_{INL} (I_{INH})

Input current of the digital input.

Crosstalk

A measure of unwanted signal that is coupled through from one channel to another as a result of parasitic capacitance.

Off Isolation

A measure of unwanted signal coupling through an off channel.

Charge Injection

A measure of the glitch impulse transferred from the digital input to the analog output during switching.

I_{DD}

Positive supply current.

I_{SS}

Negative supply current.

OUTLINE DIMENSIONS



COMPLIANT TO JEDEC STANDARDS MS-001-AB
 CONTROLLING DIMENSIONS ARE IN INCHES; MILLIMETER DIMENSIONS (IN PARENTHESES) ARE ROUNDED-OFF INCH EQUIVALENTS FOR REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN. CORNER LEADS MAY BE CONFIGURED AS WHOLE OR HALF LEADS.

Figure 28. 16-Lead Plastic Dual In-Line Package [PDIP] Narrow Body (N-16)

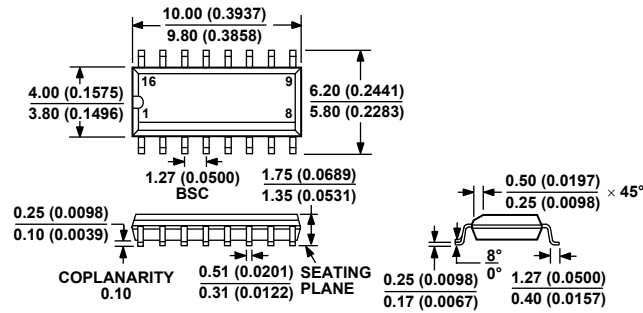
Dimensions shown in inches and (millimeters)



CONTROLLING DIMENSIONS ARE IN INCHES; MILLIMETER DIMENSIONS (IN PARENTHESES) ARE ROUNDED-OFF INCH EQUIVALENTS FOR REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN.

Figure 29. 16-Lead Ceramic Dual In-Line Package [CERDIP] (Q-16)

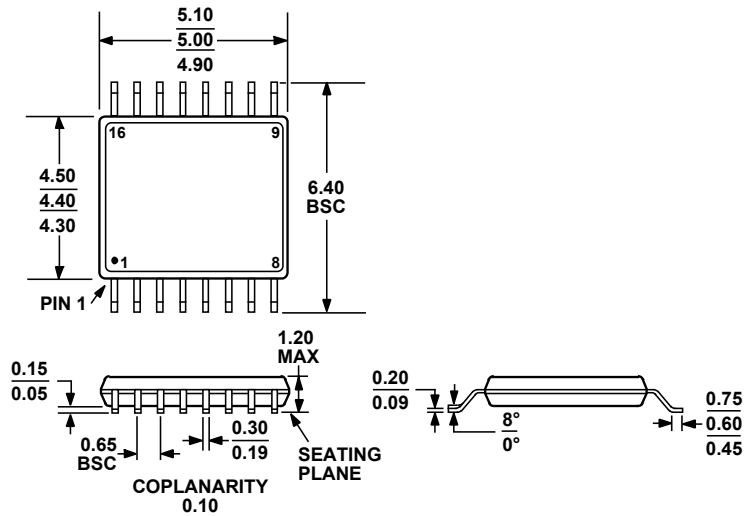
Dimensions shown in inches and (millimeters)



COMPLIANT TO JEDEC STANDARDS MS-012-AC
 CONTROLLING DIMENSIONS ARE IN MILLIMETERS; INCH DIMENSIONS
 (IN PARENTHESES) ARE ROUNDED-OFF MILLIMETER EQUIVALENTS FOR
 REFERENCE ONLY AND ARE NOT APPROPRIATE FOR USE IN DESIGN.

Figure 30. 16-Lead Standard Small Outline Package [SOIC_N]
 Narrow Body
 (R-16)

Dimensions shown in millimeters and (inches)



COMPLIANT TO JEDEC STANDARDS MO-153-AB

Figure 31. 16-Lead Thin Shrink Small Outline Package [TSSOP]
 (RU-16)

Dimensions shown in millimeters

ADG408/ADG409

ORDERING GUIDE

| Model | Temperature Range | Package Description | Package Option |
|-------------------------------|-------------------|--|----------------|
| ADG408BN | -40°C to +85°C | 16-Lead Plastic Dual In-Line Package [PDIP] | N-16 |
| ADG408BNZ ¹ | -40°C to +85°C | 16-Lead Plastic Dual In-Line Package [PDIP] | N-16 |
| ADG408BR | -40°C to +85°C | 16-Lead Narrow Body Small Outline Package [SOIC_N] | R-16 |
| ADG408BR-REEL | -40°C to +85°C | 16-Lead Narrow Body Small Outline Package [SOIC_N] | R-16 |
| ADG408BR-REEL7 | -40°C to +85°C | 16-Lead Narrow Body Small Outline Package [SOIC_N] | R-16 |
| ADG408BRU | -40°C to +85°C | 16-Lead Thin Shrink Small Outline Package [TSSOP] | RU-16 |
| ADG408BRU-REEL | -40°C to +85°C | 16-Lead Thin Shrink Small Outline Package [TSSOP] | RU-16 |
| ADG408BRU-REEL7 | -40°C to +85°C | 16-Lead Thin Shrink Small Outline Package [TSSOP] | RU-16 |
| ADG408BRUZ ¹ | -40°C to +85°C | 16-Lead Thin Shrink Small Outline Package [TSSOP] | RU-16 |
| ADG408BRUZ-REEL ¹ | -40°C to +85°C | 16-Lead Thin Shrink Small Outline Package [TSSOP] | RU-16 |
| ADG408BRUZ-REEL7 ¹ | -40°C to +85°C | 16-Lead Thin Shrink Small Outline Package [TSSOP] | RU-16 |
| ADG408BRZ ¹ | -40°C to +85°C | 16-Lead Narrow Body Small Outline Package [SOIC_N] | R-16 |
| ADG408BRZ-REEL ¹ | -40°C to +85°C | 16-Lead Narrow Body Small Outline Package [SOIC_N] | R-16 |
| ADG408BRZ-REEL7 ¹ | -40°C to +85°C | 16-Lead Narrow Body Small Outline Package [SOIC_N] | R-16 |
| ADG408TQ | -55°C to +125°C | 16-Lead Ceramic Dual In-Line Package [CERDIP] | Q-16 |
| ADG408BCHIPS | | DIE | |
| ADG409BN | -40°C to +85°C | 16-Lead Plastic Dual In-Line Package [PDIP] | N-16 |
| ADG409BNZ ¹ | -40°C to +85°C | 16-Lead Plastic Dual In-Line Package [PDIP] | N-16 |
| ADG409BR | -40°C to +85°C | 16-Lead Narrow Body Small Outline Package [SOIC_N] | R-16 |
| ADG409BR-REEL | -40°C to +85°C | 16-Lead Narrow Body Small Outline Package [SOIC_N] | R-16 |
| ADG409BR-REEL7 | -40°C to +85°C | 16-Lead Narrow Body Small Outline Package [SOIC_N] | R-16 |
| ADG409BRU | -40°C to +85°C | 16-Lead Thin Shrink Small Outline Package [TSSOP] | RU-16 |
| ADG409BRU-REEL | -40°C to +85°C | 16-Lead Thin Shrink Small Outline Package [TSSOP] | RU-16 |
| ADG409BRU-REEL7 | -40°C to +85°C | 16-Lead Thin Shrink Small Outline Package [TSSOP] | RU-16 |
| ADG409BRUZ ¹ | -40°C to +85°C | 16-Lead Thin Shrink Small Outline Package [TSSOP] | RU-16 |
| ADG409BRUZ-REEL ¹ | -40°C to +85°C | 16-Lead Thin Shrink Small Outline Package [TSSOP] | RU-16 |
| ADG409BRUZ-REEL7 ¹ | -40°C to +85°C | 16-Lead Thin Shrink Small Outline Package [TSSOP] | RU-16 |
| ADG409BRZ ¹ | -40°C to +85°C | 16-Lead Narrow Body Small Outline Package [SOIC_N] | R-16 |
| ADG409BRZ-REEL ¹ | -40°C to +85°C | 16-Lead Narrow Body Small Outline Package [SOIC_N] | R-16 |
| ADG409BRZ-REEL7 ¹ | -40°C to +85°C | 16-Lead Narrow Body Small Outline Package [SOIC_N] | R-16 |
| ADG409TQ | -55°C to +125°C | 16-Lead Ceramic Dual In-Line Package [CERDIP] | Q-16 |

¹ Z = Pb-free part.



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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